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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of:
Ken Chen

Confirmation Number: 4186

Serial No.: 10/058,473

Group Art Unit: 2823

Examiner: TOLEDO, FERNANDO

Filed: 01/28/2002

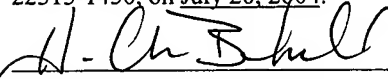
TKHR Docket No. 252016-1040

Top-Team Ref. 0503-A30594US

For: **ENHANCED ADHESION STRENGTH BETWEEN MOLD RESIN AND
POLYIMIDE**

Certificate of Mailing

I hereby certify that this correspondence is being deposited with
the United States Postal Service as first class mail, postage
prepaid, in an envelope addressed to: Mail Stop Amendment;
Commissioner for Patents, P.O. Box 1450, Alexandria, VA
22313-1450, on July 20, 2004.



Signature – Hui Chin Barnhill

AMENDMENT AND RESPONSE TO OFFICE ACTION

Mail Stop –Amendment
Assistant Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

The Office Action mailed April 20, 2004 has been carefully considered. In response
thereto, please enter the following amendments and consider the following remarks.